

IN THE CLAIMS:

1. (Currently Amended) A circuit board comprising:

a core plate;

a buildup layer formed on the core plate including at least a first insulation ~~layers~~ layer and a first conductor ~~layers~~ layer alternately stacked on each other; [[and]]

a surface conductive layer formed on the buildup layer and serving as a terminal electrode for connection to an electronic component; and

a deformation-interrupting section continuously extending through the ~~insulation layers between the conductor layers in contact with the conductor layers~~ buildup layer from the first conductor layer, through the first insulation layer and to the surface conductive layer, the deformation-interrupting section being formed of a material having a lower thermal expansion coefficient and a higher Young's modulus than the first insulation ~~layers~~ layer, the deformation-interrupting section interrupting deformation of the first insulation ~~layers~~ layer when there is a change in ambient temperature or an external force is applied to the circuit board.

2. (Withdrawn) The circuit board according to claim 1, wherein the deformation-interrupting section is formed of an insulator.

3. (Withdrawn) The circuit board according to claim 2, wherein the insulator is made of ceramic.

4. (Original) The circuit board according to claim 1, wherein the deformation-interrupting section is formed of a conductor.

5. (Original) The circuit board according to claim 4, wherein the conductor is formed of a material selected from the group consisting of Sn-Pb alloy solder, lead-free solder, Mo paste and W paste.

6. (Withdrawn) A method of forming a circuit board comprising:
forming an first inner conductor layer on a core plate;
forming an first interlevel insulator layers on the inner conductor layer;
forming a hole through the first interlevel insulator layers;
filling the hole with an insulator or a conductor, thereby forming a deformation-interrupting section, the insulator or the conductor having a lower thermal expansion coefficient and a higher Young's modulus than the first interlevel insulator layers;
forming an second inner conductor layer on the first interlevel insulator layers with the deformation-interrupting section;
forming a buildup layer having the interlevel insulator layers and the inner conductor layers are alternately stacked upon each other; and
forming the wire or the electrode on the buildup layer.

7. (Withdrawn) The method according to claim 6, wherein a ceramic paste is used as a material of the deformation-interrupting section.

8. (Withdrawn) The method according to claim 6, wherein a material selected from the group consisting of Sn-Pb alloy solder, lead-free solder, Mo paste and W paste is used as a material of the deformation-interrupting section.

9. (New) The circuit board according to claim 1, further comprising a second conductor layer, wherein the deformation-interrupting section extends through the second conductor layer.

10. (New) The circuit board according to claim 9, further comprising a second insulation layer, wherein the deformation-interrupting section continuously extends through the first and second insulation layers.

11. (New) The circuit board according to claim 10, wherein the deformation-interrupting section being formed of a material having a lower thermal expansion coefficient and a higher Young's modulus than the first and second insulation layers, the deformation-interrupting section interrupting deformation of the first and second insulation layers when there is a change in ambient temperature or an external force is applied to the circuit board.